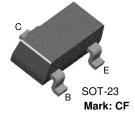


# BSS79C

## **NPN General Purpose Amplifier**

- This device is for use as a medium power amplifier and swith requiring collector currents up to 500mA.
- · Sourced from process 19.
- See BCW65C for characteristics.



# **Absolute Maximum Ratings \*** T<sub>a</sub>=25°C unless otherwise noted

Symbol	Parameter	Value	Units	
V <sub>CEO</sub>	Collector-Emitter Voltage	40	V	
V <sub>CBO</sub>	Collector-Base Voltage	75	V	
V <sub>EBO</sub>	Emitter-Base Voltage	6.0	V	
I <sub>C</sub>	Collector Current - Continuous	800	mA	
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Junction Temperature Range	-55 ~ +150	°C	

<sup>\*</sup> These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

- These ratings are based on a maximum junction temperature of 150 degrees C.
   These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.

### Electrical Characteristics Ta=25°C unless otherwise noted

Symbol	Parameter	Test Condition	Min.	Max.	Units	
Off Charac	Off Characteristics					
V <sub>(BR)CEO</sub>	Collector-Emitter Breakdown Voltage	$I_C = 10 \text{mA}, I_B = 0$	75		V	
V <sub>(BR)CBO</sub>	Collector-Base Breakdown Voltage	$I_C = 10\mu A, I_E = 0$	40		V	
V <sub>(BR)EBO</sub>	Emitter-Base Breakdown Voltage	$I_E = 10\mu A, I_C = 0$	6.0		V	
I <sub>CBO</sub>	Collector-Cutoff Current	V <sub>CB</sub> = 60V		10	nA	
		$V_{CB} = 60V, T_a = 150^{\circ}C$		10	μΑ	
I <sub>EBO</sub>	Emitter-Cutoff Current	$V_{EB} = 3.0V, I_{C} = 0$		10	nA	
On Charac	On Characteristics *					
h <sub>FE</sub>	DC Current Gain	$I_C = 150 \text{mA}, V_{CE} = 10 \text{V}$	100	300		
V <sub>CE(sat)</sub>	Collector-Emitter Saturation Voltage	I <sub>C</sub> = 150mA, I <sub>B</sub> = 15mA		0.3	V	
		$I_C = 500 \text{mA}, I_B = 50 \text{mA}$		1.0	V	
Small Sign	nal Characteristics					
f <sub>T</sub>	Current Gain - Bandwidth Product	$I_C = 20 \text{mA}, V_{CE} = 20 \text{V}, f = 100 \text{MHz}$		250	MHz	
C <sub>CB</sub>	Collector-Base Capacitance	$V_{CB} = 10V, I_E = 0, f = 1.0MHz$		8.0	pF	
Switching	Characteristics					
t <sub>d</sub>	Delay Time	$V_{CC} = 30V, V_{BE(OFF)} = 0.5V,$		10	ns	
t <sub>r</sub>	Rise Time	I <sub>C</sub> = 150mA, I <sub>B1</sub> = 15mA		10	ns	
t <sub>s</sub>	Storage Time	V <sub>CC</sub> = 30V, I <sub>C</sub> = 150mA,		265	ns	
t <sub>f</sub>	Fall Time	$I_{B1} = I_{B2} = 15mA$		60	ns	

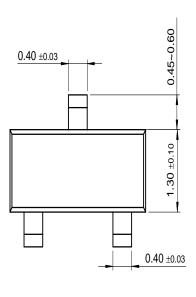
Thermal Characteristics Ta	<sub>a</sub> =25°C unless otherwise noted
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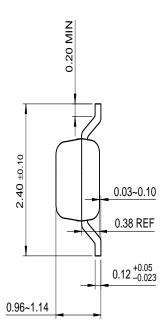
Symbol	Parameter	Max.	Units
P <sub>D</sub>	Total Device Dissipation	350	mW
	Derate above 25°C	2.8	mW/°C
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	357	°C/W

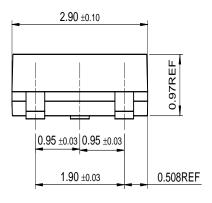
<sup>\*</sup> Device mounted on FR-4 PCB 400mm × 40mm × 1.5mm

# **Package Dimensions**

# SOT-23







Dimensions in Millimeters

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### PRODUCT STATUS DEFINITIONS

### **Definition of Terms**

Datasheet Identification	Product Status	Definition
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No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
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